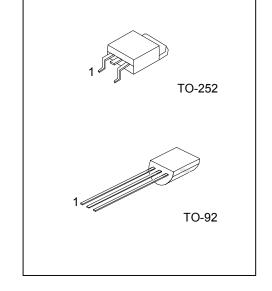
UTC UNISONIC TECHNOLOGIES CO., LTD

1N65Q-TA **Power MOSFET**

1A, 650V N-CHANNEL **POWER MOSFET**

DESCRIPTION

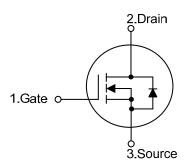
The UTC 1N65Q-TA is a high voltage MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.



FEATURES

- * $R_{DS(ON)} \le 9.5\Omega$ @ $V_{GS} = 10V$, $I_D = 0.5A$
- * Fast switching capability
- * Avalanche energy specified
- * Improved dv/dt capability, high ruggedness

SYMBOL



ORDERING INFORMATION

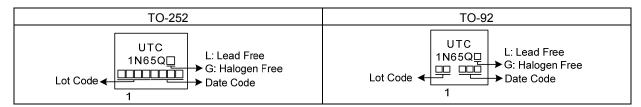
Ordering Number		Dookogo	Pin Assignment			Dooking	
Lead Free	Halogen Free	Package	1	2	3	Packing	
1N65QL-TN3-R	1N65QG-TN3-R	TO-252	G	D	S	Tape Reel	
1N65QL-T92-B	1N65QG-T92-B	TO-92	G	D	S	Tape Box	
1N65QL-T92-K	1N65QG-T92-K	TO-92	G	D	S	Bulk	

Pin Assignment: G: Gate D: Drain S: Source Note:



www.unisonic.com.tw 1 of 7 1N65Q-TA

MARKING



■ **ABSOLUTE MAXIMUM RATINGS** (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V_{DSS}	650	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Continuous Drain Current	Continuous	I _D	1.0	Α	
Pulsed Drain Current (Note 2)	ulsed Drain Current (Note 2) Pulsed (Note 2)		4.0	Α	
Avalanche Current (Note 2)		I _{AR}	1.0	Α	
Avalanche Energy (Note 3) Single Pulsed		E _{AS}	50	mJ	
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.1	V/ns	
Power Dissipation	TO-252	В	32	W	
	TO-92	P _D	3	W	
Junction Temperature		T_J	+150	°C	
Storage Temperature		T _{STG}	-55 ~ +150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 3. L=100mH, I_{AS} =1.0A, V_{DD} =50V, R_{G} =25 Ω , Starting T_{J} = 25°C
- 4. $I_{SD} \le 1.0A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25$ °C

■ THERMAL CHARACTERISTICS

PARAMETER		SYMBOL RATINGS		UNIT	
Junction to Ambient	TO-252	0	110	°C/W	
	TO-92	θ_{JA}	140	°C/W	
Junction to Case	TO-252	0	3.91 (Note)	°C/W	
	TO-92	$\theta_{ m JC}$	41.67	°C/W	

Note: The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.



ELECTRICAL CHARACTERISTICS (T_C =25°C, unless otherwise specified)

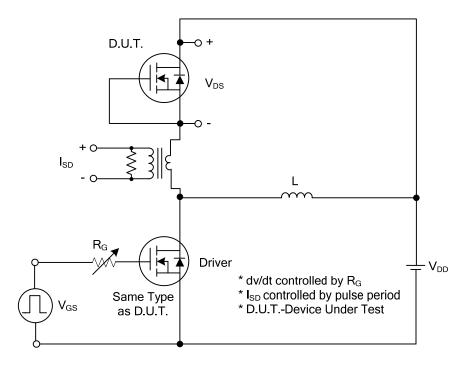
PARAMETER		SYMBOL	TEST CONDITIONS		TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV _{DSS}	$V_{GS} = 0V, I_{D} = 250\mu A$	650			V
Drain-Source Leakage Current		I _{DSS}	$V_{DS} = 650V, V_{GS} = 0V$			10	μΑ
Gate-Source Leakage Current	Forward	-	$V_{GS} = 30V, V_{DS} = 0V$			100	nA
	Reverse	I _{GSS}	$V_{GS} = -30V, V_{DS} = 0V$			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		4.0	V
Static Drain-Source On-State Resistance		R _{DS(ON)}	$V_{GS} = 10V, I_D = 0.5A$			9.5	Ω
DYNAMIC CHARACTERISTICS				ā.	-	ā.	
Input Capacitance	Input Capacitance		\\ -35\\ \\ -0\\		153		pF
Output Capacitance		Coss	V _{DS} =25V, V _{GS} =0V, -f =1MHz		20		pF
Reverse Transfer Capacitance		C_{RSS}	1 - 11011 12		3.5		pF
SWITCHING CHARACTERISTICS	3			ā.	-	ā.	
Total Gate Charge		Q_G	V _{DS} =50V, V _{GS} =10V, I _D =1.3A,		14		nC
Gate-Source Charge		Q_GS	V_{DS} =50V, V_{GS} =10V, I_{D} =1.3A, I_{G} =100µA (Note 1, 2)		1.5		nC
Gate-Drain Charge		Q_GD	IG-100µA (Note 1, 2)		1		nC
Turn-On Delay Time		t _{D (ON)}			23		ns
Turn-On Rise Time		t_R	V_{DD} = 30V, V_{GS} = 10V, I_{D} = 0.5A, R_{G} = 25 Ω (Note 1, 2)		25		ns
Turn-Off Delay Time		$t_{D(OFF)}$			60		ns
Turn-Off Fall Time		t_{F}			28		ns
DRAIN-SOURCE DIODE CHARA	CTERISTIC	CS		ā.	ā.	ā.	
Maximum Body-Diode Continuous Current		Is				1	Α
Maximum Body-Diode Pulsed Current		I _{SM}				4	Α
Drain-Source Diode Forward Voltage		V_{SD}	V _{GS} = 0 V, I _{SD} = 1.0 A			1.4	V
Reverse Recovery Time		t _{rr}			210		ns
Reverse Recovery Charge		Q _{rr}			460		nC

Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle≤2%

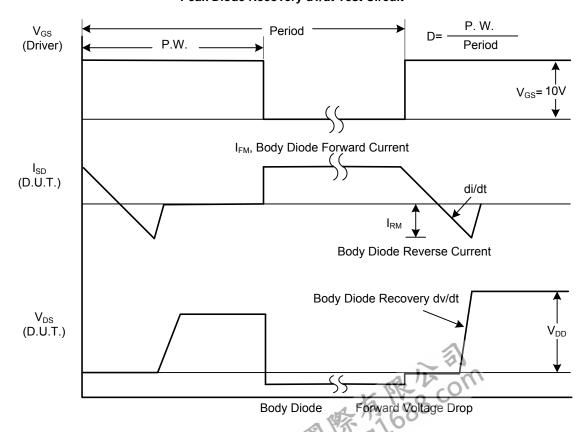


^{2.} Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS



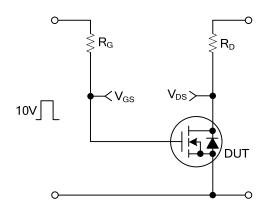
Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms

1N65Q-TA Power MOSFET

■ TEST CIRCUITS AND WAVEFORMS



90%

10%

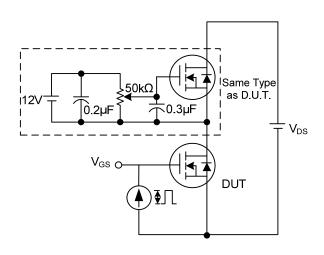
t_{d(ON)}

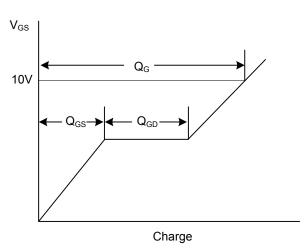
t_{ON}

t_{OFF}

itching Test Circuit

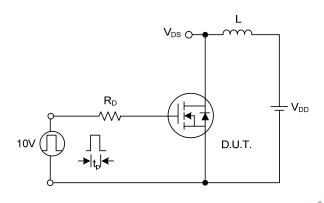
Switching Waveforms

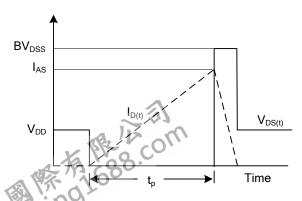




Gate Charge Test Circuit

Gate Charge Waveform

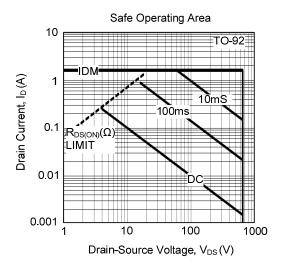




Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS



UTC assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all UTC products described or contained herein. UTC products are not designed for use in life support appliances, devices or systems where malfunction of these products can be reasonably expected to result in personal injury. Reproduction in whole or in part is prohibited without the prior written consent of the copyright owner. UTC reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.